

CONDUCTOR PASTES

1.1 Ag CONDUCTOR PASTES

| | C-1002 | C-1003 | C-1180 series | C-1190 series | C-1160 series | C-1158G |
|---|---------|--------|---------------|---------------|---------------|---------|
| Ag Content (%) | 72 | 60 | 55-65 | 65-80 | 60-67 | 60 |
| Viscosity(kcps) SC4-14 25℃10rpm | 240-360 | 50-100 | 80-200 | 30-150 | 50-120 | 10-50 |
| Resistivity (m ohm /□) | ≤5 | ≤15 | ≤10 | ≤5 | ≤10 | ≤10 |
| Fired Thickness(μm) | 8~12 | 8~12 | 8~12 | 8~15 | 9~12 | 8~12 |
| Adhesion(N) 2x2mm | ≥29.4 | | ≥25 | ≥20 | ≥15 | ≥15 |
| Aged Adhesion(N) ^{150℃24hrs} | ≥19.6 | | | | | |
| Solderability Φ _{4mmx2.85mm} 230℃ | ≥6.0 | | ≥6.0 | ≥6.0 | ≥6.0 | ≥6.0 |
| Firing(℃) | 850 | 600 | 800~820 | 550-650 | 700-850 | 550~700 |
| Solid Content (%) | | | | 68~87 | | ≥55% |
| Thinner | V-100 | | | | | |

1.2 LEAD-FREE Ag/Pd CONDUCTOR PASTES

| | C-1201 | C-1202 | C-1204 | C-1205 | C-1207A | C-1211 |
|--|---------|---------|---------|---------|----------|---------|
| Pd/Ag | 20/80 | 3/97 | 15/85 | 5/95 | 0.5/99.5 | 10/90 |
| Viscosity(Kcps) SC4-14 25℃ 10rpm | 170~210 | 170-270 | 180~230 | 170~330 | 220~320 | 230~270 |
| Resistivity (m ohm /□) | ≤20 | ≤10 | ≤20 | ≤10 | ≤5 | ≤10 |
| Fired Thickness (μm) | 8~12 | 8~12 | 8~12 | 8~12 | 8~12 | 8~12 |
| Adhesion(N)2x2mm | ≥40 | ≥35 | ≥39.2 | ≥39.2 | ≥24.5 | ≥39.2 |
| Aged Adhesion(N) ^{150℃ 24hrs} | ≥15 | ≥15 | ≥19.6 | ≥19.6 | ≥19.6 | ≥19.6 |
| SolderabilityΦ _{4mmx2.85mm} 230℃ | ≥6.0 | ≥6.5 | ≥7.0 | ≥6.0 | ≥6.0 | ≥6.5 |
| Solder Leach Resistance 230℃10 second 63Sn/37Pb | ≥3 | ≥2 | ≥3 | ≥2 | ≥1 | ≥3 |
| Firing (℃) | 850 | | | | | |
| Thinner | V-100 | | | | | |

1.3 LEAD-FREE Ag/Pt CONDUCTOR

| | C-1302 | C-1231A | C-1231G |
|--|---------|-----------|-----------|
| Main Compositions | Ag /Pt | Ag /Pt/Pd | Ag /Pt/Pd |
| Viscosity HBT SC4-14 25 ℃ 10rpm | 150~250 | 160~220 | 130~180 |
| Resistivity (m ohm / □) | ≤4 | ≤8 | ≤15 |
| Fired Thickness (um) | 8~12 | 8~12 | 8~12 |
| Adhesion(N) 2x2mm | ≥40 | ≥40 | ≥39.2 |
| Aged Adhesion(N) 150 ℃ 24hrs | ≥20 | ≥15 | ≥15 |
| Solderability 4mmx2.85mmH230 C10 秒 | ≥7.0 | ≥6.5 | ≥6.5 |
| Solder Leach Resistance 230 ℃10 second 63Sn/37Pb | ≥2 | ≥2 | ≥3 |
| Firing (℃) | 850 | | |
| Thinner | V-100 | | |

1.4 Cu / Ag CONDUCTOR

| | C-9101 |
|---------------------------------------|---------|
| Main Compositions | Cu / Ag |
| Viscosity HBT SC4-14 25 ℃10rpm | 70~150 |
| Fog (μm) | ≤8 |
| Resistivity (m ohm / □) | ≤4 |
| Fired Thickness (μm) | 13~16 |
| Adhesion (N) 2x2mm | ≥30 |
| Thinner | V-100 |